


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.		CRP/19/11361
1.3 Title of PCI		LAX Hub move preparation
1.4 Product Category		Not applicable as the change is related to HUB move and not related to Products
1.5 Issue date		2019-02-27

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Karim BILAL
2.1.2 Corporate Quality Manager	Gerard PETIT

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Logistic)	New location (hub, warehouse...)	LAX DC

4. Description of change

	Old	New
4.1 Description	LSP: Ceva Logistics Operation Services: Brokerage, Airline Recovery, Foreign Trade Zone, Crossdock, Export Processing Location: Torrance, CA Operating SQF: 13,000 Working areas Temperature, Humidity and Lux calibrated according to ST Logistics standards.	LSP: Geodis or DSV Air & Sea Operation Services: Brokerage, Airline Recovery, Foreign Trade Zone, Bonded Transfer, Export Processing, Duty Drawback Location: Carson, CA Operating SQF: 13,000 Working areas Temperature, Humidity and Lux calibrated according to ST Logistics standards.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: No change on product - Fit: No change on product - Function: No change on product. - Reliability, or Processability: NA (Not applicable).	

5. Reason / motivation for change

5.1 Motivation	Transferring LAX HUB operations to new Logistics Service Provider in Carson, CA from Ceva Logistics in Torrance, CA. The change also includes personnel, location, logistic model and the transfer of equipment, workstations, and inventories. The reason for the change is that the current agreement is ending, and the business has been awarded to a new Logistics Service Provider.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	NA
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7. Timing / schedule

7.1 Date of qualification results	2019-04-01
7.2 Intended start of delivery	2019-04-01
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11361 Public product.pdf 11361 PCI_LAX_Move_wk_0819.docx 11361 LAX_Move_Notification_letter_updated.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LSM303AGRTR	
	M24LR-DISCOVERY	
	STIEC45-30ACS	
	STLQ50C33R	
	STM32F101C8T6	
	STM32F103RCT6	
	STM32F103RGT6	
	STM32F407IGH6	
	STM32F407IGT6	
	STM32F407VGT6	
	STM8L151G6U6TR	

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